			1					1			
PCN Number:		20190821004				PCN Date:	Aug. 23, 2019				
Tit	le:	Datasheet for	DAC	8740H,	DA	C8741H					
Customer Contact: PCN Manager			<u>er</u>				ept:	Quality Services			
Ch	ange	Type:									
Assembly Site				Design			Wafer Bump Site				
Assembly Process			\boxtimes	□ Data Sheet			Wafer Bump Material				
Assembly Materials				Part number change			Wafer Bump Process				
Mechanical Specification			Щ	Test Site			Wafer Fab Site				
Packing/Shipping/Labeling			Ш	Test Process				er Fab Materials			
					- 141 - 1				Wafer Fab Process		
_					No	<u>tificatio</u>	n Details				
Description of Change:											
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.											
TEXAS INSTRUMENTS DAC8740H, DAC8741H SBASSS56D – JUNE 2017 – REVISED MAY 2019									•		
c	Changes from Revision C (December 2018) to Revision D										
Added recommended operating temperature range, T _A , to the <i>Recommended Operating Conditions</i> table											
The	e data	asheet number	will be	e chanc	aina	l .					
The datasheet number will be changing. Device Family			Change From:			Change To:					
DAC8740H, DAC8741H				SBAS85			SBAS856D				
These changes may be reviewed at the datasheet links provided.											
http://www.ti.com/product/DAC8740H											
Reason for Change:											
To accurately reflect device characteristics.											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.											
	Changes to product identification resulting from this PCN:										
None.											
Pro	oduc	t Affected:									
	DAC8740HRGER DAC8740HRG			GET	DAC8741HRGER			DAC8741HRGET			

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
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